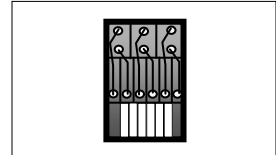


Earl J. Lum  
+1-650-430-2221  
[elum@ejlwireless.com](mailto:elum@ejlwireless.com)



**Ericsson Base Station  
BFL 901 009/1 R1A  
Model RBS6601 Main Unit**

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